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ABSTRACT OF DISCLOSURE

A microelectronic device and methods of fabricating the same comprising a microelectronic die having an active surface, a back surface, and at least one side. The microelectronic die side comprises a trench sidewall, a lip and a channel sidewall. A 5 metallization layer is disposed on the microelectronic die back surface and the trench sidewall.

FEDERAL BUREAU OF INVESTIGATION
U.S. DEPARTMENT OF JUSTICE